

SKiiP® 2

2-pack - integrated intelligent Power System

Power section

SKiiP 832GB120-406CTV

Features

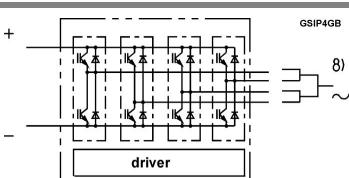
- SKiiP technology inside
- Low loss IGBTs
- CAL diode technology
- Integrated current sensor
- Integrated temperature sensor
- Integrated heat sink
- IEC 60721-3-3 (humidity) class 3k3/IE32 (SKiiP® 2 System)
- IEC 68T.1 (climate) 40/125/56 (SKiiP® 2 power section)

- 1) with assembly of suitable MKP capacitor per terminal (SEMIKRON type is recommended)
- 2) AC connection busbars must be connected by the user; copper busbars available on request

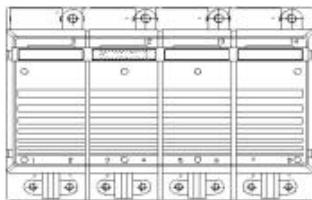
Absolute Maximum Ratings		$T_s = 25^\circ\text{C}$ unless otherwise specified		
Symbol	Conditions	Values		Units
IGBT				
V_{CES}		1200		V
$V_{CC}^1)$	Operating DC link voltage	900		V
V_{GES}		± 20		V
I_C	$T_s = 25 \text{ (70)}^\circ\text{C}$	800 (600)		A
Inverse diode				
$I_F = -I_C$	$T_s = 25 \text{ (70)}^\circ\text{C}$	800 (600)		A
I_{FSM}	$T_j = 150^\circ\text{C}$, $t_p = 10 \text{ ms}$; sin.	5760		A
I^2t (Diode)	Diode, $T_j = 150^\circ\text{C}$, 10 ms	166		kA²s
$T_{j1}(T_{stg})$		- 40 (- 25) ... + 150 (125)		°C
V_{isol}	AC, 1 min. (mainterminals to heat sink)	3000		V

Characteristics		$T_s = 25^\circ\text{C}$ unless otherwise specified		
Symbol	Conditions	min.	typ.	max.
IGBT				
V_{CEsat}	$I_C = 700 \text{ A}$, $T_j = 25 \text{ (125)}^\circ\text{C}$	2,6 (3,1)	3,1	V
V_{CEO}	$T_j = 25 \text{ (125)}^\circ\text{C}$	1,2 (1,3)	1,5 (1,6)	V
r_{CE}	$T_j = 25 \text{ (125)}^\circ\text{C}$	1,9 (2,5)	2,3 (2,9)	mΩ
I_{CES}	$V_{GE} = 0 \text{ V}$, $V_{CE} = V_{CES}$, $T_j = 25 \text{ (125)}^\circ\text{C}$	(40)	1,6	mA
$E_{on} + E_{off}$	$I_C = 700 \text{ A}$, $V_{CC} = 600 \text{ V}$ $T_j = 125^\circ\text{C}$, $V_{CC} = 900 \text{ V}$		210	mJ
			370	mJ
$R_{CC' + EE'}$	terminal chip, $T_j = 125^\circ\text{C}$	0,13		mΩ
L_{CE}	top, bottom	3,8		nH
C_{CHC}	per phase, AC-side	5,6		nF
Inverse diode				
$V_F = V_{EC}$	$I_F = 600 \text{ A}$, $T_j = 25 \text{ (125)}^\circ\text{C}$	2,1 (1,9)	2,6	V
V_{TO}	$T_j = 25 \text{ (125)}^\circ\text{C}$	1,3 (1)	1,4 (1,1)	V
r_T	$T_j = 25 \text{ (125)}^\circ\text{C}$	1,3 (1,5)	1,7 (2)	mΩ
E_r	$I_C = 700 \text{ A}$, $V_{CC} = 600 \text{ V}$ $T_j = 125^\circ\text{C}$, $V_{CC} = 900 \text{ V}$	24		mJ
		31		mJ
Mechanical data				
M_{dc}	DC terminals, SI Units	6	8	Nm
M_{ac}	AC terminals, SI Units	13	15	Nm
w	SKiiP® 2 System w/o heat sink	3,5		kg
w	heat sink	8,5		kg
Thermal characteristics (P16 heat sink; 275m³/h); "r" reference to temperature sensor				
$R_{th(j-s)I}$	per IGBT		0,032	K/W
$R_{th(j-s)D}$	per diode		0,094	K/W
$R_{th(s-a)}$	per module		0,033	K/W
Z_{th}	R_i (mK/W) (max. values)		$\tau_{ai}(s)$	
	1 2 3 4	1 2 3 4		
$Z_{th(j-r)I}$	4 25 4	1 0,13 0,001		
$Z_{th(j-r)D}$	10 72 11	1 0,13 0,001		
$Z_{th(r-a)}$	1,6 22 7 2,4	494 165 20 0,03		

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Case S 4



SKiiP® 2

2-pack - integrated intelligent Power System

2-pack integrated gate driver

SKiiP 832GB120-406CTV

Gate driver features

- CMOS compatible inputs
- Wide range power supply
- Integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- Short circuit protection
- Over current protection
- Over voltage protection (option)
- Power supply protected against under voltage
- Interlock of top/bottom switch
- Isolation by transformers
- Fibre optic interface (option for GB-types only)
- IEC 68T.1 (climate) 25/85/56 (SKiiP® 2 gate driver)

Absolute Maximum Ratings

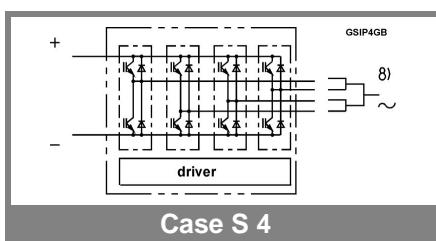
Symbol	Conditions	Values	Units
V_{S1}	stabilized 15 V power supply	18	V
V_{S2}	unstabilized 24 V power supply	30	V
V_{iH}	input signal voltage (high)	15 + 0,3	V
dV/dt	secondary to primary side	75	kV/μs
V_{isolIO}	input / output (AC, r.m.s., 2s)	3000	Vac
V_{isol12}	output 1 / output 2 (AC, r.m.s., 2s)	1500	Vac
f_{max}	switching frequency	19	kHz
$T_{op} (T_{stg})$	operating / storage temperature	- 25 ... + 85	°C

Characteristics

Symbol	Conditions	min.	typ.	max.	Units
V_{S1}	supply voltage stabilized	14,4	15	15,6	V
V_{S2}	supply voltage non stabilized	20	24	30	V
I_{S1}	$V_{S1} = 15 \text{ V}$	$290+550*f/f_{max}+1,3*(I_{AC}/A)$			mA
I_{S2}	$V_{S2} = 24 \text{ V}$	$220+400*f/f_{max}+1,0*(I_{AC}/A)$			mA
V_{iT+}	input threshold voltage (High)	11,2			V
V_{iT-}	input threshold voltage (Low)			5,4	V
R_{IN}	input resistance	10			kΩ
$t_{d(on)IO}$	input-output turn-on propagation time	1,2			μs
$t_{d(off)IO}$	input-output turn-off propagation time	1,6			μs
$t_pERRRESET$	error memory reset time	9			μs
t_{TD}	top / bottom switch : interlock time	3,3			μs
$I_{analog OUT}$	8 V corresponds to max. current of 15 V supply voltage (available when supplied with 24 V)	800			A
$I_{Vs1outmax}$	output current at pin 12/14		50		mA
I_{AOmax}	logic low output voltage		5		mA
V_{O1}	logic high output voltage		0,6		V
V_{OH}			30		V
I_{TRIPSC}	over current trip level ($I_{analog OUT} = 10 \text{ V}$)	1000			A
I_{TRIPLG}	ground fault protection		110		A
T_{tp}	over temperature protection		120		°C
U_{DCTRIP}	trip level of U_{DC} -protection ($U_{analog OUT} = 9 \text{ V}$); (option)	900			V

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